

# M1FS4

# Schottky Barrier Diodes 40V, 1.33A

#### **Feature**

- Small SMD
- · High Recovery Speed
- Low V<sub>F</sub>
- Based on AEC-Q101
- Pb free terminal
- RoHS:Yes

### **OUTLINE**

Package (House Name): M1F
Package (JEDEC Code): DO-219AA similar

## **Equivalent circuit**



## Absolute Maximum Ratings (unless otherwise specified: Tl=25°C)

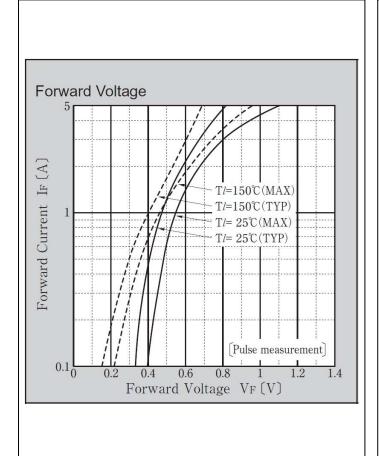
Item	Symbol	Conditions	Ratings	Unit
Storage temperrature	Tstg		-55 to 150	°C
Junction temperature	Tj		-55 to 150	°C
Repetitive peak reverse voltage	V <sub>RRM</sub>		40	V
Repetitive peak surge reverse voltage	$V_{RRSM}$	Pulse width 0.5ms, duty=1/40	45	V
Average forward current	I <sub>F</sub> (AV)	50Hz sine wave, Resistance load, On alumina substrate, Ta=25°C %	1.33	Α
Average forward current	I <sub>F</sub> (AV)	50Hz sine wave, Resistance load, On glass-epoxy substrate, Ta=25°C ※	0.87	Α
Surge forward current	I <sub>FSM</sub>	50Hz sine wave, Non-repetitive, 1cycle, Peak value, Tj=25°C	30	А
Repetitive peak surge reverse power	P <sub>RRSM</sub>	Pulse width 10μs, Tj=25°C	60	W

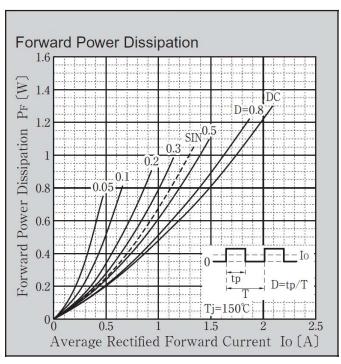
**<sup>\* :</sup> See the original Specifications** 

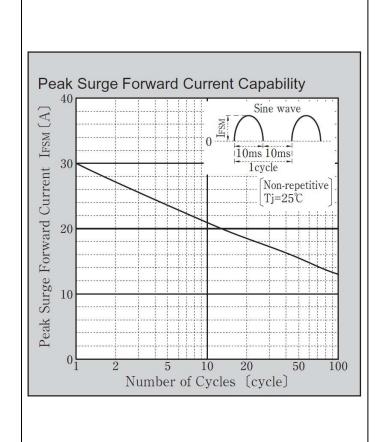
## **Electrical Characteristics** (unless otherwise specified: Tl=25°C)

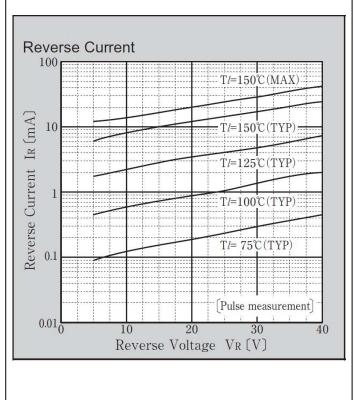
Item	Symbol	Conditions	Ratings			Unit
			MIN	TYP	MAX	Unit
Forward voltage	$V_{F}$	IF=1.1A, Pulse measurement			0.55	V
Reverse current	I <sub>R</sub>	VR=40V, Pulse measurement			0.8	mA
Total capacitance	Ct	f=1MHz, VR=10V		50		pF
Thermal resistance	Rth(j-l)	Junction to lead			20	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On alumina substrate ※			108	°C/W
Thermal resistance	Rth(j-a)	Junction to ambient, On glass-epoxy substrate *			186	°C/W

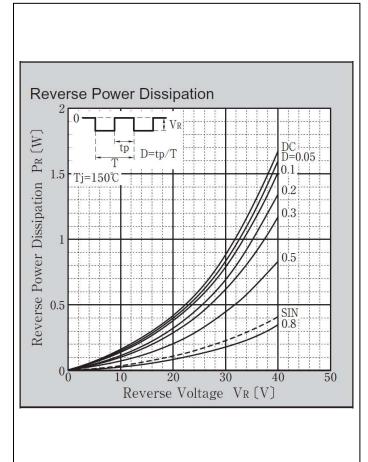
## **CHARACTERISTIC DIAGRAMS**

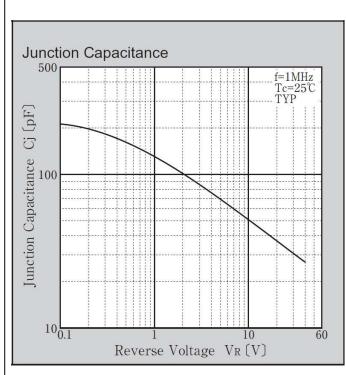


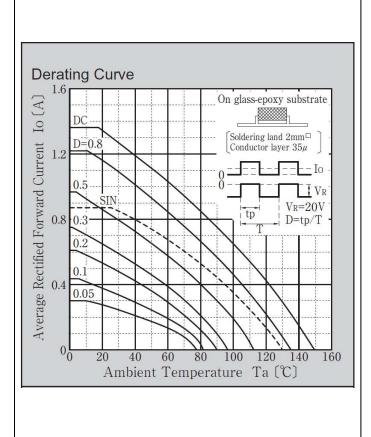


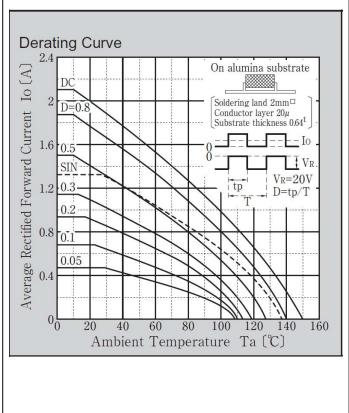


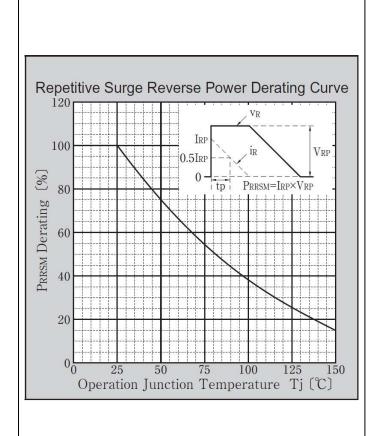


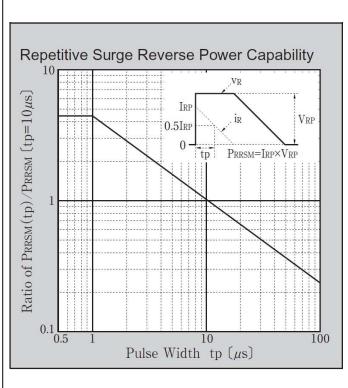










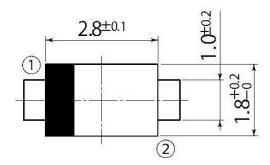


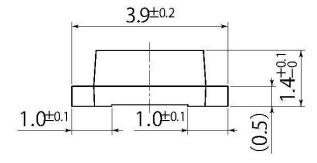
## unit:mm

scale: 10/1

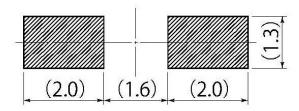
**B2** 

JEDEC Code	DO-219AA similar		
JEITA Code	_		
House Name	M1F		









## Referential Soldering Pad

• Optimize soldering pad to the board design and soldering condition.

#### **Notes**

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#### [Specific applications]

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